



Features

- Low operating and clamping voltage
- Up to four I/O Lines of Protection
- low capacitance
- Low Leakage
- Low operating voltage:3.3V
- Flow-Through design

IEC COMPATIBILITY (EN61000-4)

- IEC 61000-4-2 (ESD) $\pm 30\text{kV}$ (air), $\pm 30\text{kV}$ (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 5A (8/20 μs)

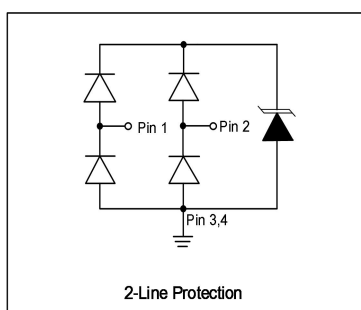
Mechanical Characteristics

- DFN1610-6L package
- Marking: Marking Code
- Packaging: Tape and Reel
- RoHS Compliant

Applications

- Digital Visual Interface(DVI)
- MDDI Ports
- Display Port TM Interface
- PCI Express
- High Definition Multi-Media Interface(HDMI)
- HDMI Interfaces

Schematic & PIN Configuration



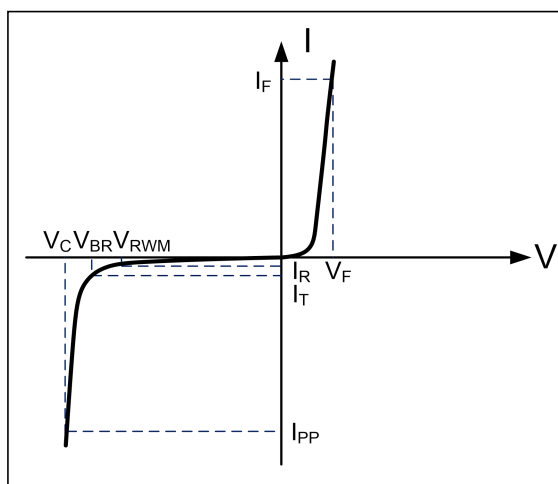
Pin	Identificaion
1,2	Input line
5,6	Output Lines (No Internal Connection)
3,4	Ground

Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PP}	60	Watts
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{PP}	5	A
Operating Temperature	T_J	-55 to + 125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Parameters (T=25°C)

Symbol	Parameter
I_{PP}	Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Reverse Stand-Off Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F



Electrical Characteristics

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				3.3	V
Reverse Breakdown Voltage	V_{BR}	$I_t = 1\text{mA}$	3.7			V
Reverse Leakage Current	I_R	$V_{RWM} = 3.3\text{V}$, $T = 25^\circ\text{C}$			500	nA
Clamping Voltage	V_C	$I_{PP} = 5\text{A}$, $t_p = 8/20\mu\text{s}$ I/O pin to GND		10	12	V
Dynamic Resistance ^{1,2}	R_{DYN}	TLP=0.2/100ns		0.27		Ω
ESD Clamping Voltage ¹	V_C	$I_{PP} = 4\text{A}$, $t_p = 0.2/100\text{ns}$ (TLP)		8.0		V
ESD Clamping Voltage ¹	V_C	$I_{PP} = 16\text{A}$, $t_p = 0.2/100\text{ns}$ (TLP)		11.3		V
Junction Capacitance	C_j	$V_R = 0\text{V}$, $f = 1\text{MHz}$ I/O pin to GND		0.8	1.2	pF
		$V_R = 0\text{V}$, $f = 1\text{MHz}$ Between I/O pins		0.4	0.6	pF

Notes : 1、TLP Setting : $t_p = 100\text{ns}$, $t_r = 0.2\text{ns}$, I_{TLP} and V_{TLP} sample window: $t_1 = 70\text{ns}$ to $t_2 = 90\text{ns}$.

2、Dynamic resistance calculated from $I_{PP} = 4\text{A}$ to $I_{PP} = 16\text{A}$ using “Best Fit”.

Typical Characteristics

Figure 1: Peak Pulse Power vs. Pulse Time

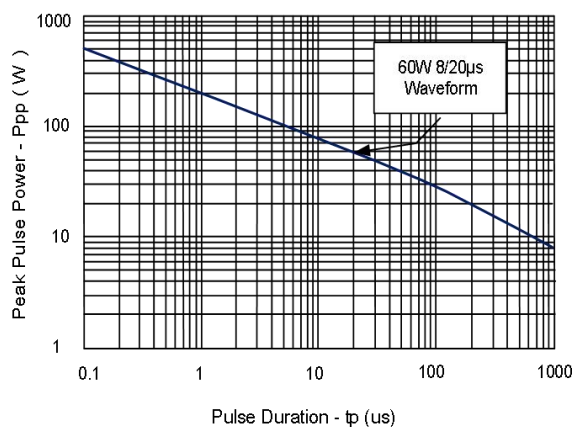


Figure 2: Power Derating curve

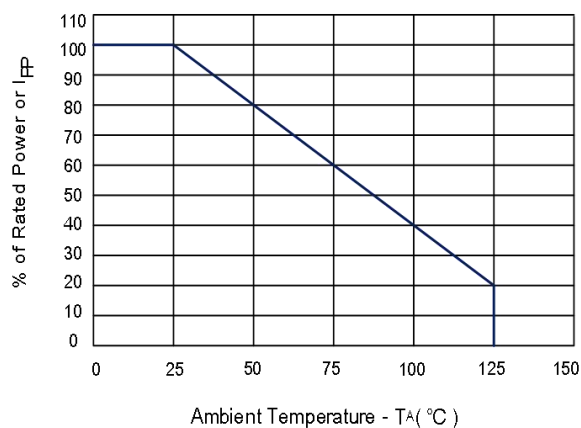


Figure 3: Clamping Voltage vs. Peak Pulse Current

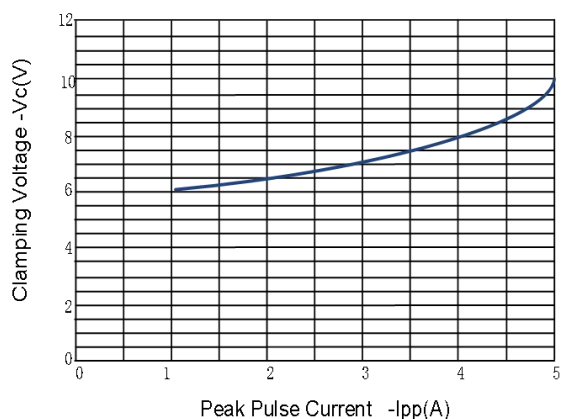


Figure 4: Normalized Junction Capacitance vs. Reverse Voltage

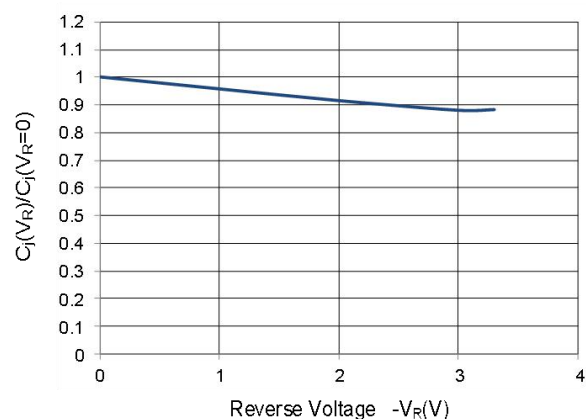


Figure 5: 8/20 μs Pulse Waveform

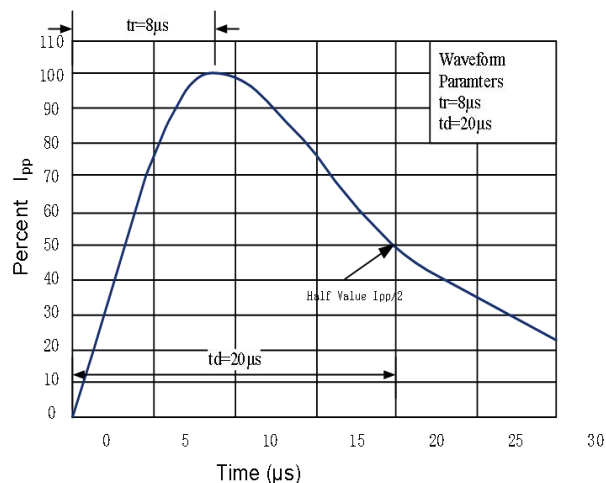
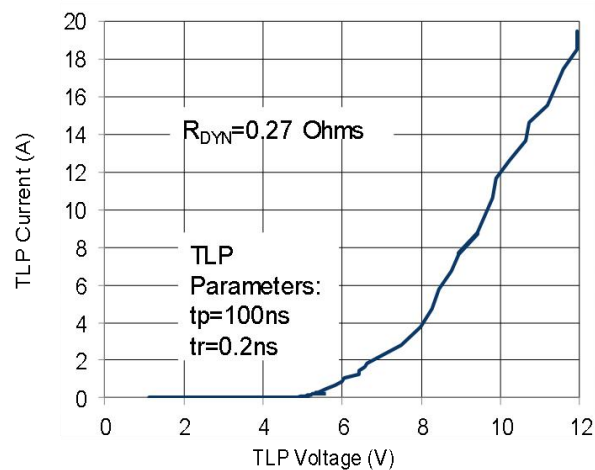
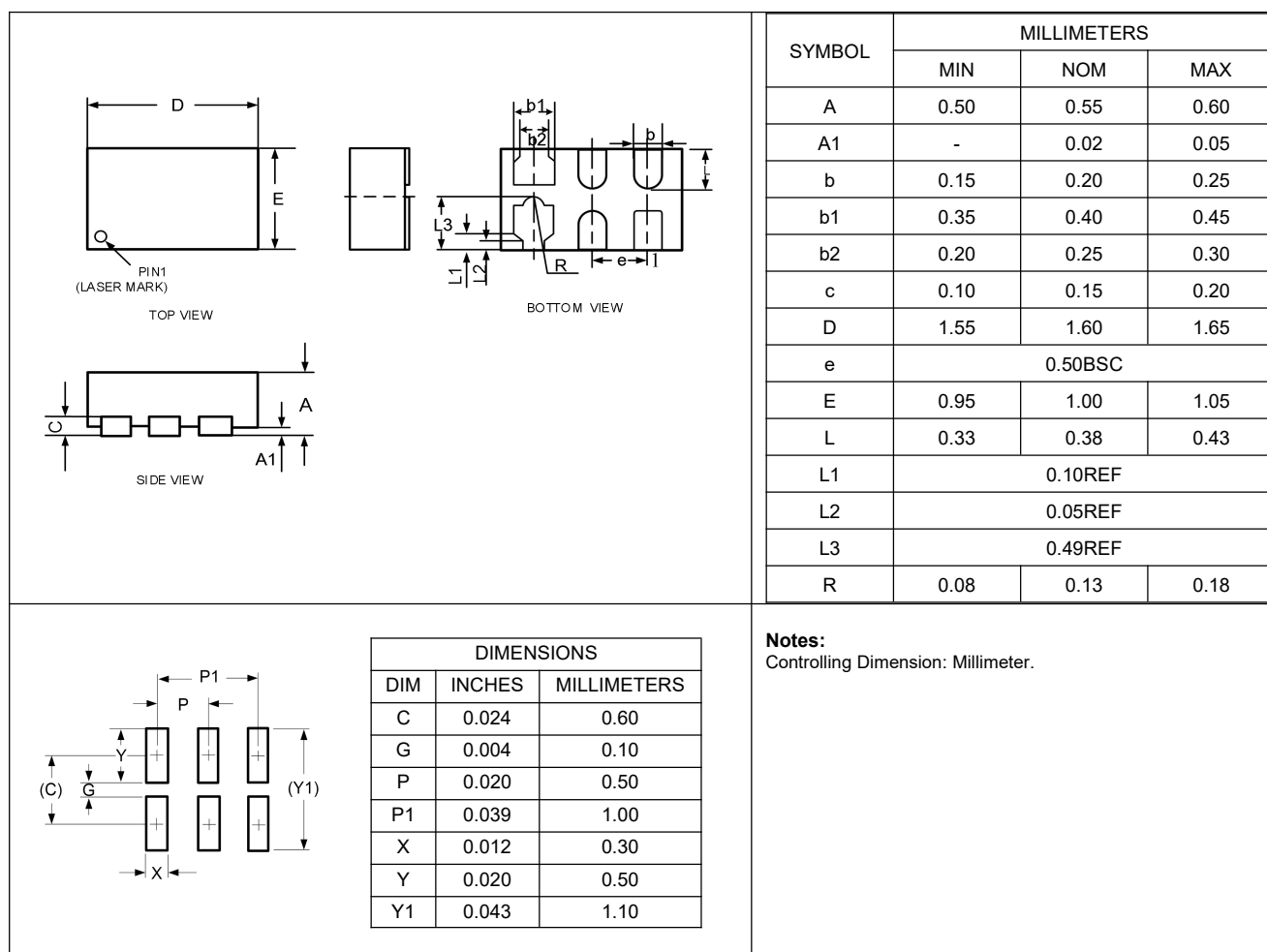


Figure 6: TLP I-V Curve



Outline Drawing – DFN1610-6L



Marking Codes

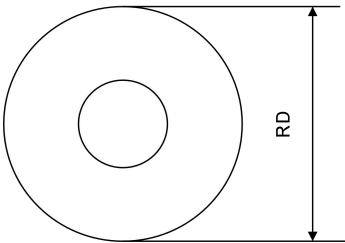
Part Number	Marking Code
ES332R2PA	1R2P

Package Information

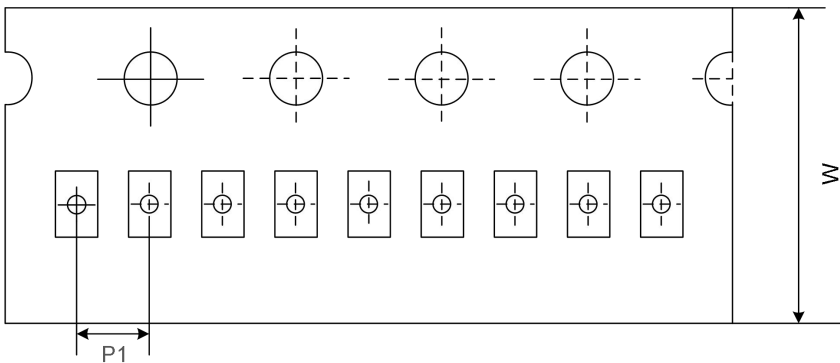
Qty: 10k/Reel

Tape And Reel Information

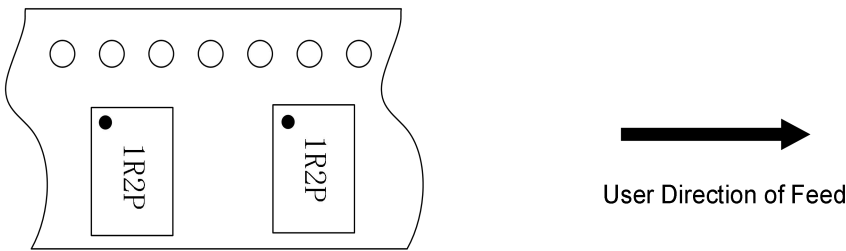
Reel Dimensions



Tape Dimensions



Quadrant Assignments For PIN1 Orientation In Tape



RD	Reel Dimensions	7 inch
W	Overall width of the carrier tape	8 mm
P1	Pitch between successive cavity centers	2mm

Revision History

No.	Version	Date	Revision Item	Request	Function and characteristic checking	Package dimension checking	Typos checking
1	1.0	2018-09-15	Released Version	Qi Shu Kun	Qi Shu Kun	Liu Jia Ying	Liu Jia Ying